BONDING THE STARS





Specifications

Mechanics

X, Y table Working area 100 x 115 mm

Resolution 0.25 μm, repeatability < 2 μm

Z-axis 60 mm

Speed up to ≤20 wires / min.

Bond head Wedge-Wedge Thin-Wire (Au/Al)

Axis of rotation ± 360°

Ultrasonic system 60KHz / 100kHz optional 140KHz

Wire size 17,5μm up to 75μm

Control

Heating-controller Integrated in machine 0 - 250°C

Computer Dual Core PC, 1,6 GHz processor,

4 GB RAM, Ethernet, USB 4x + 4x frontside

Monitor TFT flat screen

Operation system Windows 7

Printer All Windows-compatible printers can be installed

All bonding parameters can be printed

Work holder ø 80mm or 4x4"

Heated work holder ø 80mm and optional 4x4"

(mech. / vacuum)

(Attention: 4x4" up to 200°C; 80 mm up to 250°C)

5630

Semi-automatic Wedge-Wedge-Bonder

The semi-automatic Wedge-Wedge Bonder 5630 fills the gap between the manual Wedge-to the automatic-bonder. He is on basis 5600-series fully PC controlled and allows any number of bonds to be programmed.

Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds are executed automatically.

Two operating modes are available: Single bond for repair of various bond samples and making single bonds (manual-automatic) and multi wire for teaching and bonding chips or various bond samples (semi and fully automatic).

The 5630 can also be used as Gold Wire or Alu Heavy Wire as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software.

change over time: approx. 5 minutes.

Ask us for more information!

Other features

Programming: Automatic bonding of hybrids or COB

with programmable X/Y table

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Work holders



For components up to 4 x 4" Vacuum and mech. clamping

Heated Substrathalter optional



For components up to 4 x 4"
Vacuum and mech. clamping
heated



for components up to Ø 80 mm Vacuum and mech. clamping heated

More Work holders available on request.

Head Parking System For storing of temporary not required bondhead

or pull- and shear-heads.

Can be mounted on the left or right side of the ma-

chine

General

Camera With cross hair targeting for positioning of bonds

Microscope Stereoskop Standard 40x, other

Microscopes optional

Lighting 20 W halogen spot light, optional LED direct light

Incident light optional

Dimensions Height 70 cm, width 70 cm, depth 65 cm; approx. 70

kg

Supplies 100...240 VAC, single-phase, 50/60 Hz, max. 500

VA

Connections Air 6 bar, vacuum 0,7 bar ø 6 mm

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